

PZT2222A, SPZT2222A

NPN Silicon Planar Epitaxial Transistor

This NPN Silicon Epitaxial transistor is designed for use in linear and switching applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

Features

- PNP Complement is PZT2907AT1
- The SOT-223 Package Can be Soldered Using Wave or Reflow
- SOT-223 Package Ensures Level Mounting, Resulting in Improved Thermal Conduction, and Allows Visual Inspection of Soldered Joints
- The Formed Leads Absorb Thermal Stress During Soldering, Eliminating the Possibility of Damage to the Die
- Available in 12 mm Tape and Reel
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	40	Vdc
Collector-Base Voltage	V_{CBO}	75	Vdc
Emitter-Base Voltage (Open Collector)	V_{EBO}	6.0	Vdc
Collector Current	I_C	600	mAdc
Total Power Dissipation up to $T_A = 25^\circ\text{C}$ (Note 1)	P_D	1.5	W
Storage Temperature Range	T_{stg}	- 65 to +150	$^\circ\text{C}$
Junction Temperature	T_J	150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Device mounted on an epoxy printed circuit board 1.575 inches x 1.575 inches x 0.059 inches; mounting pad for the collector lead min. 0.93 inches².

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.3	$^\circ\text{C}/\text{W}$
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	T_L	260 10	$^\circ\text{C}$ Sec

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



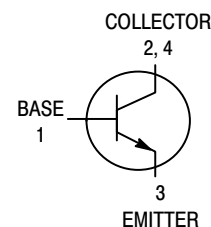
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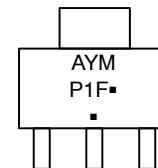
SOT-223 PACKAGE NPN SILICON TRANSISTOR SURFACE MOUNT



SOT-223 (TO-261)
CASE 318E-04
STYLE 1



MARKING DIAGRAM



A = Assembly Location
Y = Year
M = Month Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
PZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
SPZT2222AT1G	SOT-223 (Pb-Free)	1,000 Tape & Reel
PZT2222AT3G	SOT-223 (Pb-Free)	4,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage (I _C = 10 mAdc, I _B = 0)	V _{(BR)CEO}	40	-	Vdc
Collector-Base Breakdown Voltage (I _C = 10 μAdc, I _E = 0)	V _{(BR)CBO}	75	-	Vdc
Emitter-Base Breakdown Voltage (I _E = 10 μAdc, I _C = 0)	V _{(BR)EBO}	6.0	-	Vdc
Base-Emitter Cutoff Current (V _{CE} = 60 Vdc, V _{BE} = - 3.0 Vdc)	I _{BEX}	-	20	nAdc
Collector-Emitter Cutoff Current (V _{CE} = 60 Vdc, V _{BE} = - 3.0 Vdc)	I _{CEX}	-	10	nAdc
Emitter-Base Cutoff Current (V _{EB} = 3.0 Vdc, I _C = 0)	I _{EBO}	-	100	nAdc
Collector-Base Cutoff Current (V _{CB} = 60 Vdc, I _E = 0) (V _{CB} = 60 Vdc, I _E = 0, T _A = 125°C)	I _{CBO}	- -	10 10	nAdc μAdc

ON CHARACTERISTICS

DC Current Gain (I _C = 0.1 mAdc, V _{CE} = 10 Vdc) (I _C = 1.0 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc, T _A = - 55°C) (I _C = 150 mAdc, V _{CE} = 10 Vdc) (I _C = 150 mAdc, V _{CE} = 1.0 Vdc) (I _C = 500 mAdc, V _{CE} = 10 Vdc)	h _{FE}	35 50 70 35 100 50 40	- - - - 300 - -	-
Collector-Emitter Saturation Voltages (I _C = 150 mAdc, I _B = 15 mAdc) (I _C = 500 mAdc, I _B = 50 mAdc)	V _{CE(sat)}	- -	0.3 1.0	Vdc
Base-Emitter Saturation Voltages (I _C = 150 mAdc, I _B = 15 mAdc) (I _C = 500 mAdc, I _B = 50 mAdc)	V _{BE(sat)}	0.6 -	1.2 2.0	Vdc
Input Impedance (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)	h _{ie}	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)	h _{re}	- -	8.0x10 ⁻⁴ 4.0x10 ⁻⁴	-
Small-Signal Current Gain (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)	h _{fe}	50 75	300 375	-
Output Admittance (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz) (V _{CE} = 10 Vdc, I _C = 10 mAdc, f = 1.0 kHz)	h _{oe}	5.0 25	35 200	μmhos
Noise Figure (V _{CE} = 10 Vdc, I _C = 100 μAdc, f = 1.0 kHz)	F	-	4.0	dB

DYNAMIC CHARACTERISTICS

Current-Gain – Bandwidth Product (I _C = 20 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)	f _T	300	-	MHz
Output Capacitance (V _{CB} = 10 Vdc, I _E = 0, f = 1.0 MHz)	C _c	-	8.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc, I _C = 0, f = 1.0 MHz)	C _e	-	25	pF

SWITCHING TIMES (T_A = 25°C)

Delay Time	(V _{CC} = 30 Vdc, I _C = 150 mAdc, I _{B(on)} = 15 mAdc, V _{EB(off)} = 0.5 Vdc) Figure 1	t _d	-	10	ns
Rise Time		t _r	-	25	
Storage Time	(V _{CC} = 30 Vdc, I _C = 150 mAdc, I _{B(on)} = I _{B(off)} = 15 mAdc) Figure 2	t _s	-	225	ns
Fall Time		t _f	-	60	

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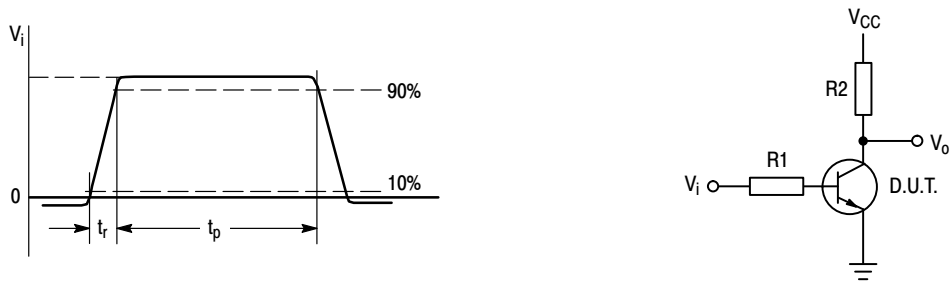


Figure 1. Input Waveform and Test Circuit for Determining Delay Time and Rise Time

$V_i = -0.5 \text{ V to } +9.9 \text{ V}$, $V_{CC} = +30 \text{ V}$, $R_1 = 619 \Omega$, $R_2 = 200 \Omega$.

PULSE GENERATOR:

PULSE DURATION t_p 3 200 ns
RISE TIME t_r 3 2 ns
DUTY FACTOR δ = 0.02

OSCILLOSCOPE:

INPUT IMPEDANCE $Z_i > 100 \text{ k}\Omega$
INPUT CAPACITANCE $C_i < 12 \text{ pF}$
RISE TIME $t_r < 5 \text{ ns}$

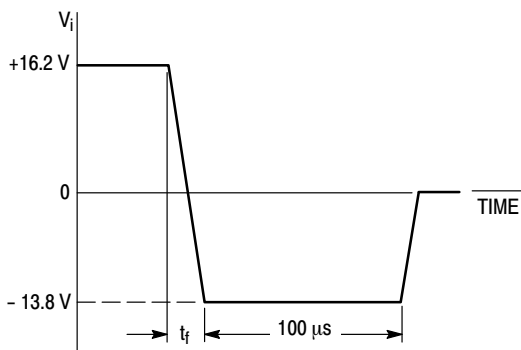
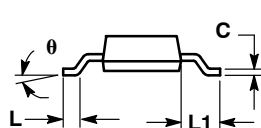
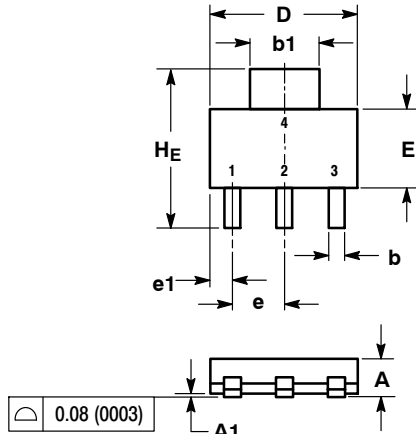


Figure 2. Input Waveform and Test Circuit for Determining Storage Time and Fall Time

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PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE N

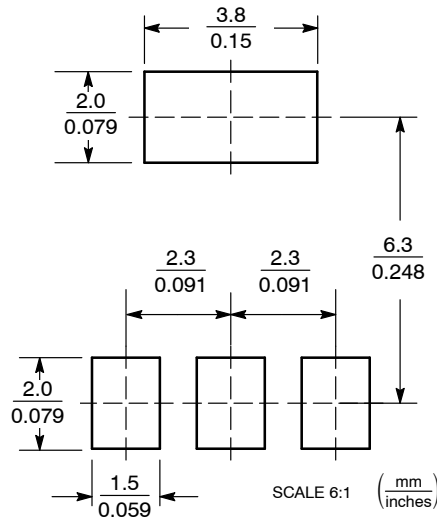


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
e	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20	---	---	0.008	---	---
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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